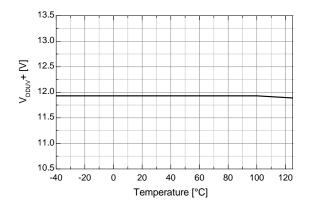
Typical Characteristics



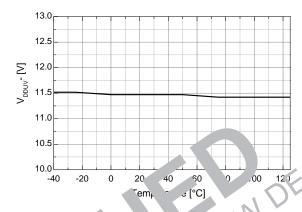
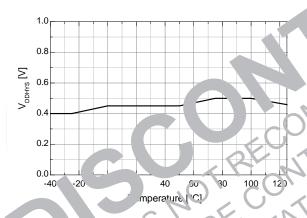
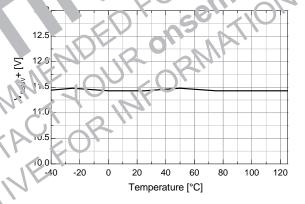


Figure 5. V_{DD} UVLO (+) vs. Temperature

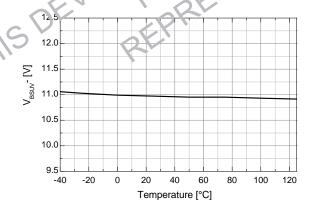
Fig. re V_{DD} / 'LO (-) vs. 1 emperature





rure V_{DD} UVLO hysteres sivs. Temperature

Figure 8. V_{BS} UVLO (+) vs. Temperature



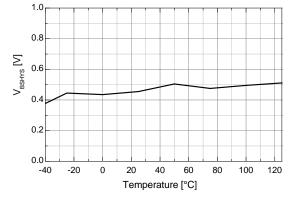
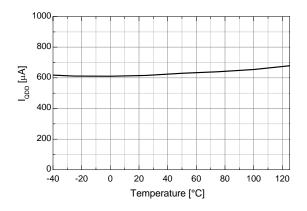


Figure 9. V_{BS} UVLO (-) vs. Temperature

Figure 10. V_{BS} UVLO Hysteresis vs. Temperature



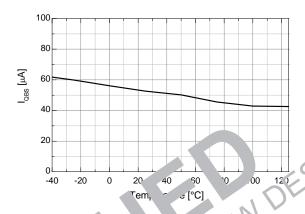
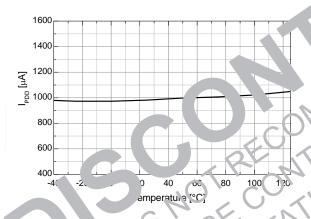
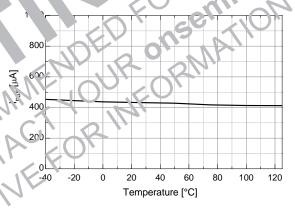


Figure 11. V_{DD} Quiescent Current vs. Temperature

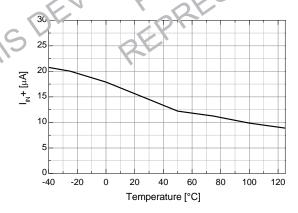
Figure V_E Quie: ent Current vs. Temperature





F. re 1 V_{DD} Operating Current vs. Temperature

Figure 14. V_{BS} Operating Current vs. Temperature





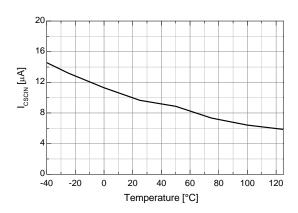
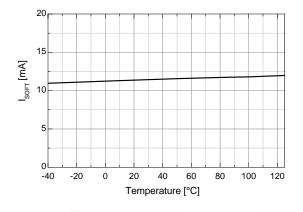


Figure 16. I_{CSCIN} vs. Temperature



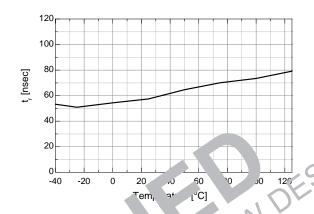
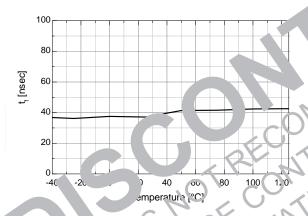
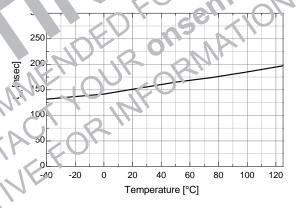


Figure 17. I_{SOFT} vs. Temperature

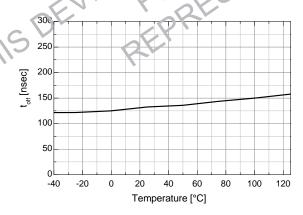
Figure 8. in-on ising Time vs. Temperature





nure). Turn-off Failing Time vs. Temperature

Figure 20. Turn-on Delay Time vs. Temperature



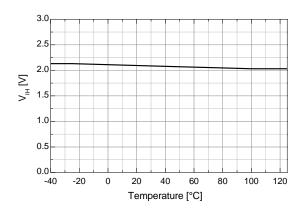
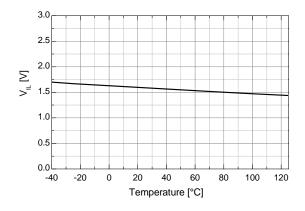


Figure 21. Turn-off Delay Time vs. Temperature

Figure 22. Logic Input High Voltage vs. Temperature



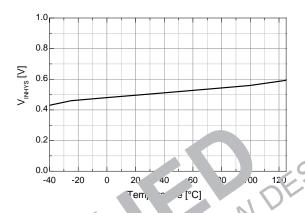
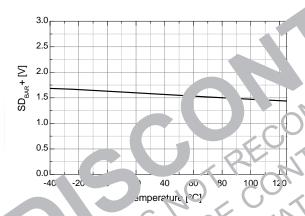
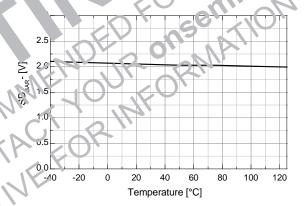


Figure 23. Logic Input Low Voltage vs. Temperature

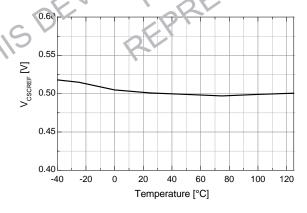
Figure . L. 'c Inp Hysteres's vs. Temperature





Fure 2 . SD Positive Threshold vs. Ten perature

Figure 26. SD Negative Threshold vs. Temperature



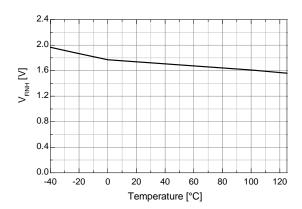
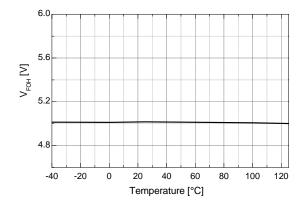


Figure 27. V_{CSCREF} vs. Temperature

Figure 28. Fault Input High Voltage vs. Temperature



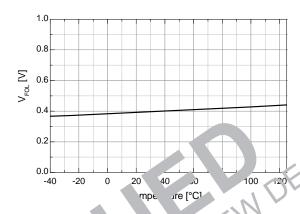
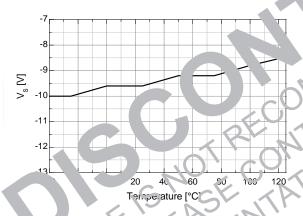


Figure 29. Fault Output High Voltage vs. Temperature

Figure 30. 'aul. 'utr Low Voltage vs. Temperature



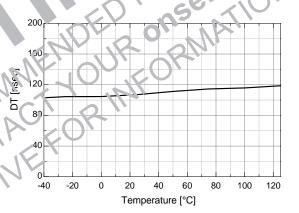


Figure 31. Allowable Mediative V_S Voltage for Signal Propagation to High Side vs. Temperature

Figure 32. Dead Time vs. Temperature

Switching Time Definitions

The overall switching timing waveforms definition of FAN7384 as shown Figure 33.

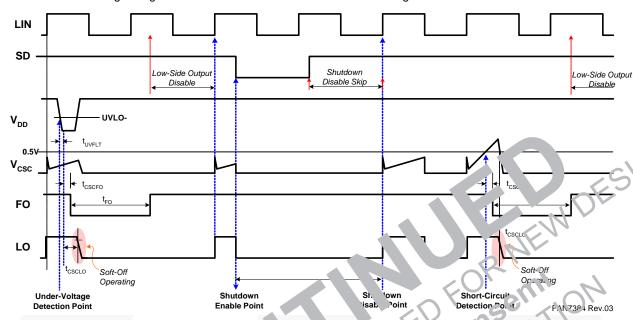


Figure 33. Timing Way of orms Definition

Typical Application Information

1. Protection Function

1.1 Under-Voltage Lockout (UVLO)

The high- and low-side drivers include under-voltage lockout (UVLO) protection circuitry that monitors the supply voltage (V_{DD}) and bootstrap capacitor voltage (V_{BS}) independently. It can be designed to prevent malfunction when V_{DD} and V_{BS} are lower than the specified threshold voltage. Moreover, the UVLO hysteresis prevents chattering during power supply transitions. If the supply voltage (V_{DD}) maintains an under-voltage condition over under-voltage filtering times (typically 16 μ s), the fault and soft-off circuits are activated, as shown Figure 34.

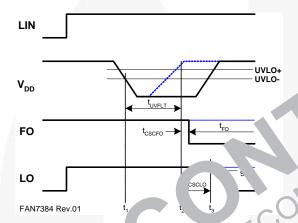


Figure 34. Waveform for Un pr-Voltage Lockout

1.2 Shoot 'rough Pr ention Function

T' FA. '38 has a shoot-through prevention circuitry to the moning shapping and low-side inputs. It can be declined prevent outputs of high and low-side turning on at the time, as shown Figure 35 and 26.

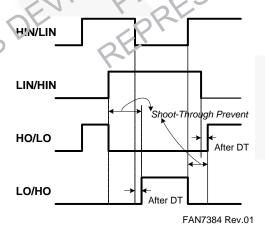


Figure 35. Waveforms for Shoot-Through Prevention

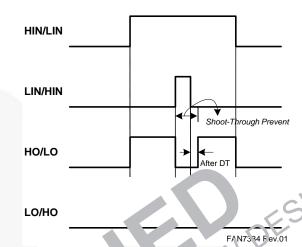


Figure 36. W reform, for .oot-Through Prevention

3 to sign of the strong restriction of the s

The FA 7384 has o er-current detection circuitry that more has the current-by-current sensing resistor connected from the low-side switch sour x_0 (V_{SL}) to ground.

It is a built in time-filer from the over-current event to prevent malfunction from a noise source, such as leading edge or lise in inductive load application, as shown Figure 37.

The sensing current is calculated as follows:

$$I_{\rm CS} = \frac{V_{\rm CSCREF}}{R_{\rm CS}} [A] \tag{1}$$

where,

V_{CSCREF}: Reference voltage of current sense comparator

R_{CS}: Current sensing resistor

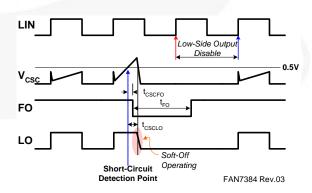


Figure 37. Waveforms for Short-Circuit Protection

2. Layout Considerations

For optimum performance, considerations must be taken during printed circuit board (PCB) layout.

2.1 Supply Capacitors

If the output stages are able to quickly turn on a switching device with a high value of current, the supply capacitors must be placed as close as possible to the device pins (V_{DD} and GND for the ground-tied supply, V_{B} and V_{S} for the floating supply) to minimize parasitic inductance and resistance.

2.2 Gate-Drive Loop

Current loops behave like antennae, able to receive and transmit noise. To reduce the noise coupling/emission and improve the power switch turn-on and off performance, gate-drive loops must be reduced as much as possible.

2.3 Ground Plane

To minimize noise coupling, the ground plane should not be placed under or near the high-voltage floating side.

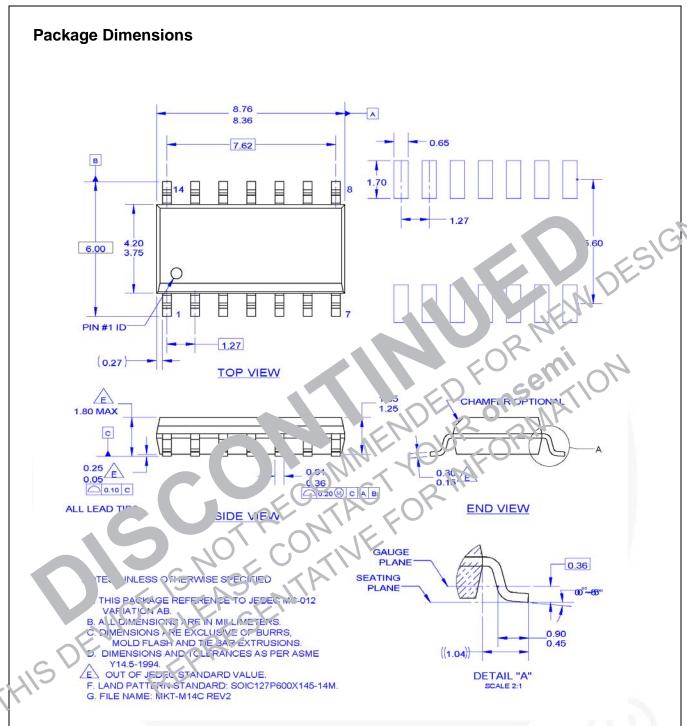


Figure 38. 14-Lead, Small Outline Integrated Circuit (SOIC), Non-JEDEC, .150 Inch Narrow Body, 225SOP

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